## **Key Scanning IC**

# ON

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#### Overview

The LC75700T is a key scanning LSI that accepts input from up to 30 keys and can control up to four general purpose output ports. Therefore it can reduce the number of lines to the front panel in application systems.

#### **Features**

- Key input function for up to 30 keys.
- General-purpose output ports for up to four pins.
- A key scan is performed only when a key is pressed, and thus power dissipation is reduced.
- Serial data I/O supports CCB\* format communication with the system controller.
- Switching between the key scan output port and general purpose output port functions can be controlled by the control data.
- The RES pin is provided. This pin disables key scanning, and forces the general-purpose output ports to the low level.
- RC oscillator circuit



TSSOP20 4.4x6.5 / TSSOP20 (225 mil)

#### **ORDERING INFORMATION**

| Device          | Package                      | Shipping (Qty / Packing) |
|-----------------|------------------------------|--------------------------|
| LC75700T-MPB-E  | TSSOP20(225mil)<br>(Pb-Free) | 70 / Fan-Fold            |
| LC75700T-TLM-E  | TSSOP20(225mil)<br>(Pb-Free) | 2000 / Tape &Reel        |
| LC75700TS-MPB-E | TSSOP20(225mil)<br>(Pb-Free) | 70 / Fan-Fold            |
| LC75700TS-TLM-E | TSSOP20(225mil)<br>(Pb-Free) | 2000 / Tape &Reel        |

<sup>†</sup> For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub\_link/Collateral/BRD8011-D.PDF

<sup>\*</sup> Computer Control Bus (CCB) is an ON Semiconductor's original bus format and the bus addresses are controlled by ON Semiconductor.

#### **Specifications**

## Absolute Maximum Ratings at Ta = 25 °C, $V_{SS} = 0~V$

| Parameter                          | Symbol              | Conditions                          | Ratings                       | Unit |  |
|------------------------------------|---------------------|-------------------------------------|-------------------------------|------|--|
| Maximum supply voltage             | V <sub>DD</sub> max | V <sub>DD</sub> max V <sub>DD</sub> |                               | V    |  |
| Innut voltage                      | V <sub>IN</sub> 1   | V <sub>IN</sub> 1 CE, CL, DI, RES   |                               | V    |  |
| Input voltage                      | V <sub>IN</sub> 2   | OSC, KI1 to KI5                     | -0.3 to V <sub>DD</sub> + 0.3 | v    |  |
| Output valtage                     | V <sub>OUT</sub> 1  | DO                                  | -0.3 to +7.0                  | V    |  |
| Output voltage                     | V <sub>OUT</sub> 2  | OSC, KS1 to KS6, P1 to P4           | -0.3 to V <sub>DD</sub> + 0.3 | ]    |  |
| Output ourrent                     | I <sub>OUT</sub> 1  | KS1 to KS6                          | 1                             | mA   |  |
| Output current                     | I <sub>OUT</sub> 2  | P1 to P4                            | 5                             | IIIA |  |
| Allowable power dissipation Pd max |                     | Ta = 85°C                           | 150                           | mW   |  |
| Operating temperature Topr         |                     |                                     | -40 to +85                    | °C   |  |
| Storage temperature                | Tstg                |                                     | -50 to +150                   | °C   |  |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### Allowable Operating Ranges at Ta = -40 to +85°C, $V_{SS} = 0$ V

| Darameter                        | Cumbal            | Symbol Conditions —                         |                 | Ratings             |      |                     | Unit |
|----------------------------------|-------------------|---|-----------------|---------------------|------|---------------------|------|
| Parameter                        | Symbol            |   |                 | min                 | typ  | max                 |      |
| Supply voltage                   | V <sub>DD</sub>   | V <sub>DD</sub>                             |                 | 2.7                 | 5.0  | 5.5                 | V    |
| Input high level voltage         | V <sub>IH</sub> 1 | CE, CL, DI, RES                             |                 | 0.8 V <sub>DD</sub> |      | 5.5                 | V    |
| Input high level voltage         | V <sub>IH</sub> 2 | KI1 to KI5                                  |                 | 0.6 V <sub>DD</sub> |      | $V_{DD}$            | V    |
| Input low level voltage          | V <sub>IL</sub>   | CE, CL, DI, RES, KI1 to KI5                 |                 | 0                   |      | 0.2 V <sub>DD</sub> | V    |
| Recommended external resistance  | Rosc              | OSC   |                 |                     | 39   |                     | kΩ   |
| Recommended external capacitance | Cosc              | OSC   |                 |                     | 1000 |                     | pF   |
| Guaranteed oscillator range      | fosc              | OSC   |                 | 19                  | 38   | 76                  | kHz  |
| Low level clock pulse width      | tøL               | CL  | See figure 1.   | 160                 |      |                     | ns   |
| High level clock pulse width     | tøH               | CL  | See figure 1.   | 160                 |      |                     | ns   |
| Data setup time                  | tds               | DI, CL                                      | See figure 1.   | 160                 |      |                     | ns   |
| Data hold time                   | tdh               | DI, CL                                      | See figure 1.   | 160                 |      |                     | ns   |
| CE wait time                     | tcp               | CE, CL                                      | See figure 1.   | 160                 |      |                     | ns   |
| CE setup time                    | tcs               | CE, CL                                      | See figure 1.   | 160                 |      |                     | ns   |
| CE hold time                     | tch               | CE, CL                                      | See figure 1.   | 160                 |      |                     | ns   |
| DO output delay time             | tdc               | DO R <sub>PU</sub> = 4.7 kΩ, $C_L$ = 10 pF* | See figure 1.   |                     |      | 1.5                 | μs   |
| DO rise time                     | tdr               | DO R <sub>PU</sub> = 4.7 kΩ, $C_L$ = 10 pF* | 1 See figure 1. |                     |      | 1.5                 | μs   |

Note: \*1. Since DO is an open-drain output, these times depend on the values of the pull-up resistor  $R_{PU}$  and the load capacitance  $C_L$ .

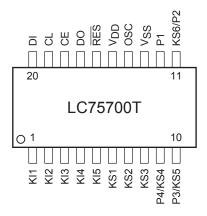
Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### **Electrical Characteristics** in the Allowable Operating Ranges

| Parameter                  | Symbol                                | Pin Name                    | Conditions   |                       | Unit                  |                       |  |     |     |     |   |
|----------------------------|---------------------------------------|-----------------------------|--|-----------------------|-----------------------|-----------------------|--|-----|-----|-----|---|
| Parameter                  | Symbol                                | Pin Name                    | Conditions   | min                   | typ                   | max                   | Offic  |     |     |     |   |
| Hysteresis                 | VH                                    | CE, CL, DI, RES, KI1 to KI5 |  |                       | 0.1 V <sub>DD</sub>   |                       | V  |     |     |     |   |
| Input high level current   | I <sub>IH</sub>                       | CE, CL, DI, RES             | V <sub>I</sub> = 5.5 V                                     |                       |                       | 5                     | μA   |     |     |     |   |
| Input low level current    | I <sub>IL</sub>                       | CE, CL, DI, RES             | V <sub>I</sub> = 0 V                                       | -5                    |                       |                       | μA   |     |     |     |   |
| Input floating voltage     | V <sub>IF</sub>                       | KI1 to KI5                  |  |                       |                       | 0.05 V <sub>DD</sub>  | V  |     |     |     |   |
| Pull-down resistance       | Б                                     | KI1 to KI5                  | V <sub>DD</sub> = 5.0 V                                    | 50                    | 100                   | 250                   | kΩ   |     |     |     |   |
| Pull-down resistance       | R <sub>PD</sub>                       | KIT to KIS                  | V <sub>DD</sub> = 3.0 V                                    | 100                   | 200                   | 500                   | K12  |     |     |     |   |
| Output off leakage current | I <sub>OFFH</sub>                     | DO                          | V <sub>O</sub> = 5.5 V                                     |                       |                       | 6                     | μA   |     |     |     |   |
|                            | V 4                                   | KS1 to KS6                  | $V_{DD}$ = 3.6 V to 5.5 V $I_{O}$ = -500 $\mu$ A           | V <sub>DD</sub> – 1.0 | V <sub>DD</sub> – 0.5 | V <sub>DD</sub> – 0.2 |  |     |     |     |   |
| Output high level voltage  | V <sub>OH</sub> 1                     |                             | $V_{DD}$ = 2.7 V to 3.6 V $I_{O}$ = -250 $\mu$ A           | V <sub>DD</sub> – 0.8 | V <sub>DD</sub> - 0.4 | V <sub>DD</sub> - 0.1 | V  |     |     |     |   |
|                            | V <sub>OH</sub> 2                     | P1 to P4                    | I <sub>O</sub> = -1 mA                                     | V <sub>DD</sub> – 0.9 |                       |                       |  |     |     |     |   |
|                            | \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | K04 +- K00                  | V <sub>DD</sub> = 3.6 V to 5.5 V<br>I <sub>O</sub> = 25 μA | 0.2                   | 0.5                   | 1.5                   |  |     |     |     |   |
| Output low level voltage   | V <sub>OL</sub> 1                     | NOL1                        | V <sub>OL</sub> 1  | V <sub>OL</sub> 1     | V <sub>OL</sub> 1     | 1 KS1 to KS6          | V <sub>DD</sub> = 2.7 V to 3.6 V<br>I <sub>O</sub> = 12.5 μA | 0.1 | 0.4 | 1.2 | V |
|                            | V <sub>OL</sub> 2                     | P1 to P4                    | I <sub>O</sub> = 1 mA                                      |                       |                       | 0.9                   |  |     |     |     |   |
|                            | V <sub>OL</sub> 3                     | DO                          | I <sub>O</sub> = 1 mA                                      |                       | 0.1                   | 0.5                   |  |     |     |     |   |
| Oscillator frequency       | fosc                                  | osc                         | Rosc = $39 \text{ k}\Omega$<br>Cosc = $1000 \text{ pF}$    | 30.4                  | 38                    | 45.6                  | kHz  |     |     |     |   |
|                            | I <sub>DD</sub> 1                     | V <sub>DD</sub>             | Key scan standby state                                     |                       |                       | 5                     |  |     |     |     |   |
| Current drain              | I <sub>DD</sub> 2                     | V <sub>DD</sub>             | V <sub>DD</sub> = 5.5 V<br>Output open<br>fosc = 38 kHz    |                       | 200                   | 400                   | μΑ   |     |     |     |   |

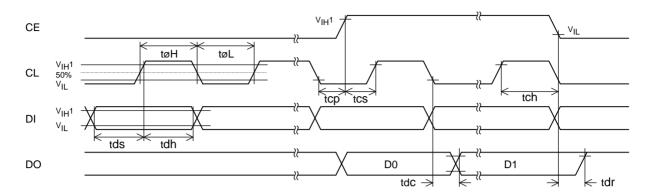
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **Pin Assignment**



Top view

## 1. When CL is stopped at the low level



## 2. When CL is stopped at the high level

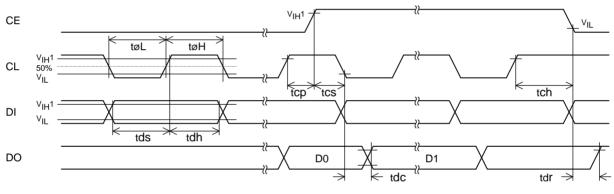
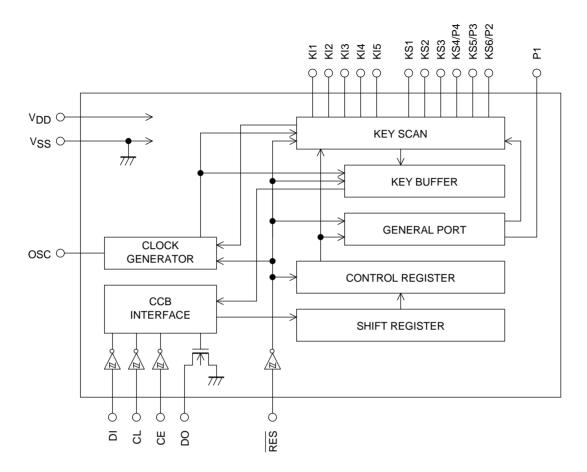


Figure 1

## **Block Diagram**

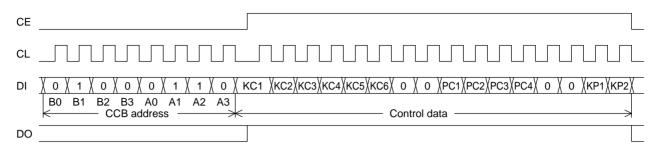


## **Pin Functions**

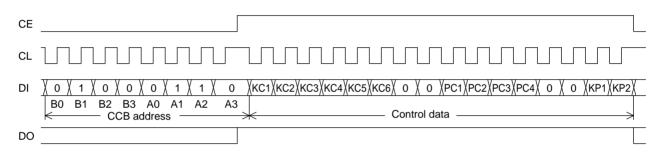
| Pin              | Pin No. | Function  | Active | I/O | Handling when unused |
|------------------|---------|---|--------|-----|----------------------|
| KI1 to KI5       | 1 to 5  | Key scan inputs. These pins have built-in pull-down resistors.  | Н      | - 1 | GND                  |
| KS1 to KS3       | 6 to 8  | Key scan outputs. Although normal key scan timing lines require diodes to be inserted in the timing lines to prevent shorts, since these outputs are unbalanced CMOS transistor outputs, these outputs will not be damaged by shorting when these outputs are used to from a key matrix.  | _      | 0   | Open                 |
| KS4/P4 to KS6/P2 | 9 to 11 | Key scan outputs and general-purpose output ports shared-function pins.  These pins can be set the key scan output ports or the general-purpose output ports by the control data "KP1 and KP2".   | 1      | 0   | Open                 |
| P1               | 12      | The P1 is general-purpose output ports.   |        | 0   | Open                 |
| osc              | 14      | Oscillator connection. An oscillator circuit is formed by connecting an external resistor and capacitor at this pin.  | _      | I/O | V <sub>DD</sub>      |
| RES              | 16      | Reset input. that re-initializes the LSI internal states. This pin must be used.  • When RES is low (V <sub>SS</sub> )  — Key scanning disabled: KS1 to KS3 = low (V <sub>SS</sub> ).  — Key scan outputs and general output ports shared-function pins: KS4/P4 to KS6/P2 = low (V <sub>SS</sub> ).  — General-purpose output port: P1 = low (V <sub>SS</sub> ).  — All the key data is reset to low.  • When RES is high (V <sub>DD</sub> )  — The states of the pins as key scan output pins or general-purpose output ports, must be set with the control data.  — And key scanning is a enabled.  Note that serial data must be transferred when RES is high. | L      | I   | GND                  |
| CE               | 18      | Serial data interface. Connections to the controller. Note that DO, being   | Н      | I   |                      |
| CL               | 19      | an open-drain output, requires a pull-up resistor. CE: Chip enable  | _      | I   | GND                  |
| DI               | 20      | CL: Synchronization clock DI: Transfer data   | _      | I   |                      |
| DO               | 17      | DO: Output data   | _      | 0   | Open                 |
| V <sub>DD</sub>  | 15      | Power supply. A voltage of between 2.7 V and 5.5 V must be supplied.  | _      | _   | _                    |
| V <sub>SS</sub>  | 13      | Ground. Must be connected to the system ground.   |        | _   | _                    |

#### **Serial Data Input**

1. When CL is stopped at the low level



2. When CL is stopped at the high level



- CCB address: 62H
   KC1 to KC6: Key scan output state setting data
- PC1 to PC4: General-purpose output port state setting data
- KP1, KP2: Selection data between the key scan output ports and the general-purpose output ports.

#### **Control Data Functions**

1.KP1, KP2: Selection data between the key scan output ports and the general-purpose output ports.

These control data bits switch the functions of the KS4/P4 to KS6/P2 output pins between the key scan output port and the general-purpose output port.

|   | KP1  | KP2 |        | Output pins |        | Maximum number | Number of general-purpose |
|---|------|-----|--------|-------------|--------|----------------|---------------------------|
|   | KF I | NF2 | KS4/P4 | KS5/P3      | KS6/P2 | of key inputs  | output ports (+ P1)       |
| Ī | 0    | 0   | KS4    | KS5         | KS6    | 30             | 0 (+1)                    |
| Ī | 1    | 0   | KS4    | KS5         | P2     | 25             | 1 (+1)                    |
| Ī | 0    | 1   | KS4    | P3          | P2     | 20             | 2 (+1)                    |
| Ī | 1    | 1   | P4     | P3          | P2     | 15             | 3 (+1)                    |

Note: KSn (n = 4 to 6): Key scan output ports Pn (n = 4 to 2): General-purpose output ports

#### 2.KC1 to KC6: Key scan output state setting data

These control data bits set the states of the key scan output pins KS1 to KS6.

| Output pins                        | KS1 | KS2 | KS3 | KS4 | KS5 | KS6 |
|------------------------------------|-----|-----|-----|-----|-----|-----|
| Key scan output state setting data | KC1 | KC2 | KC3 | KC4 | KC5 | KC6 |

For example, if the KS4/P4 to KS6/P2 output pins are set to function as key scan output ports, when KC1 to KC3 are set to 1 and KC4 to KC6 are set to 0, in the key scan standby state, the KS1 to KS3 output pins will output the high level ( $V_{DD}$ ) and the KS4 to KS6 pins will output the low level ( $V_{SS}$ ). Note that key scan output signals are not output from output pins that are set to the low level.

#### 3.PC1 to PC4: General-purpose output port state setting data

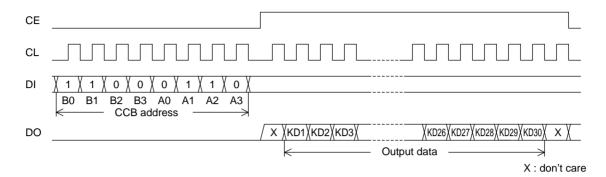
These control data bits set the states of the general-purpose output ports P1 to P4.

| Output pins                                    | P1  | P2  | P3  | P4  |
|--|-----|-----|-----|-----|
| General-purpose output port state setting data | PC1 | PC2 | PC3 | PC4 |

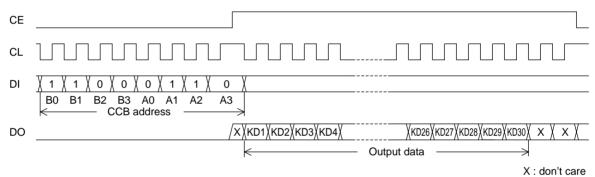
For example, if the KS4/P4 to KS6/P2 output pins are set to function as general-purpose output ports, when PC1 and PC2 are set to 1, and PC3 and PC4 are set to 0, the P1 and P2 output pins will output the high level  $(V_{DD})$ , and P3 and P4 will output the low level  $(V_{SS})$ .

#### **Serial Data Output**

#### 1. When CL is stopped at the low level



#### 2. When CL is stopped at the high level



- CCB address: 63H
- KD1 to KD30: Key data

Note: If a key data read operation is executed when DO is high, the read key data (KD1 to KD30) will be invalid.

#### **Output Data**

#### 1.KD1 to KD30: Key data

When a key matrix of up to 30 keys is formed from the KS1 to KS6 key scan output pins and the KI1 to KI5 key scan input pins and one of those key is pressed, the key output data corresponding to that key will be set to 1. The table shows the relationship between those pins and the key data bits.

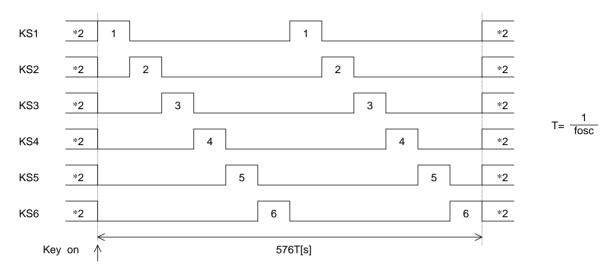
|     | KI1  | KI2  | KI3  | KI4  | KI5  |
|-----|------|------|------|------|------|
| KS1 | KD1  | KD2  | KD3  | KD4  | KD5  |
| KS2 | KD6  | KD7  | KD8  | KD9  | KD10 |
| KS3 | KD11 | KD12 | KD13 | KD14 | KD15 |
| KS4 | KD16 | KD17 | KD18 | KD19 | KD20 |
| KS5 | KD21 | KD22 | KD23 | KD24 | KD25 |
| KS6 | KD26 | KD27 | KD28 | KD29 | KD30 |

When the KS4/P4 to KS6/P2 output pins are set to function as the general-purpose output ports with the control data "KP1 and KP2", and a key matrix of up to 15 keys is formed from the KS1 to KS3 output pins and the KI1 to KI5 input pins, the KD16 to KD30 key data bits will be set to 0.

#### **Key Scan Operation Functions**

#### 1. Key scan timing

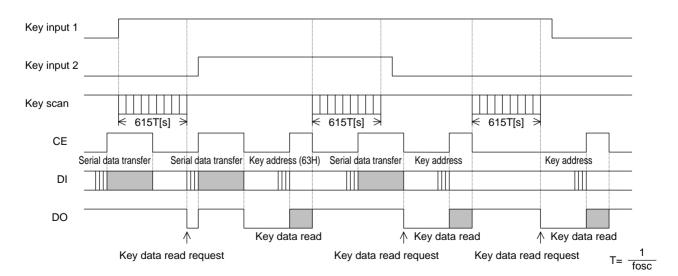
The key scan period is 288T (s). To reliably determine the on/off state of the keys, this LSI scans the keys twice and determines that a key has been pressed when the key data agrees. It outputs a key data read request (a low level on DO) 615T (s) after starting a key scan. If the key data does not agree and a key was pressed at that point, it scans the keys again. Thus this LSI cannot detect a key press shorter than 615T (s).



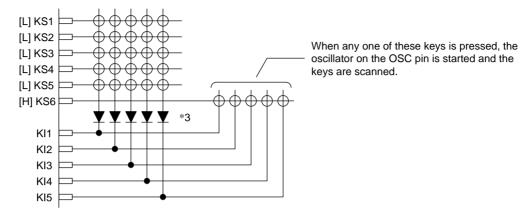
\*2. Not that the high/low states of these pins are determined by the control data, and that key scan output signals are not output from pins that are set to low.

#### 2. Key scan operation

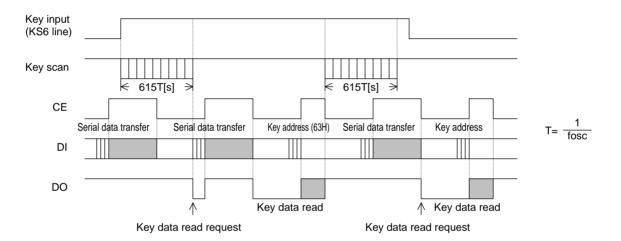
- •The pins KS1 to KS6 are set to the high or low state by the control data.
- •If a key on one of the lines corresponding to a KS1 to KS6 pin which is set high is pressed, the oscillator on the OSC pin is started and a key scan is performed. Keys are scanned until all keys are released. Multiple key presses are recognized by determining whether multiple key data bits are set.
- •If a key is pressed for longer than 615T (s) (where T = 1/fosc) this LSI outputs a key data read request (a low level on DO) to the controller. The controller acknowledges this request and reads the key data. However, if CE is high during a serial data transfer, Do will be set high.
- •After the controller reads the key data, the key data read request is cleared (DO is set high) and this LSI performs another key scan. Also note that DO being an open-drain output, requires a pull-up resistor (between  $1 \text{ k}\Omega$  and  $10 \text{ k}\Omega$ ).



Example: When control data "KP1 and KP2 = 0, KC1 to KC5 = 0, KC6 = 1" are executed. (i.e.key scanning with only KS6 high.)



\*3. These diodes are required to reliabled recognize multiple key presses of keys on the KS6 line when state with only KS6 high, as in the above example. That is, these diodes prevent incorrect operations due to sneak currents in the KS6 key scan output signal keys on the KS1 to KS5 lines are pressed at the same time.



#### Multiple Key Presses

Although this LSI is capable of key scanning without inserting diodes for dual key presses, triple key presses on the KI1 to KI5 input pin lines, or multiple key presses on the KS1 to KS6 output pin lines, multiple presses other than these cases may result in keys that were not pressed recognized as having been pressed. Therefore, a diode must be inserted in series with each key. Applications that do not recognize multiple key presses of three or more keys should check the key data for three or more 1 bits and ignore such data.

#### **System Reset**

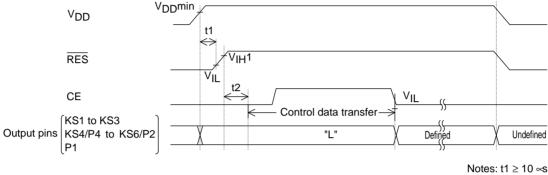
When the power is first applied, the state of function is undefined, so it must be initialized by RES = "L"

#### 1.Reset methods

This LSI stopprts the reset methods described below.

When a system reset is applied, key scanning is disabeled, the key data is reset, and the general-purpose output ports are set to and held at the low level  $(V_{SS})$ .

Set  $\overline{RES}$  = "H" after the  $\overline{RES}$  = "L" period. And key scanning become possible by the control data are transferred.



Notes: t1 ≥ 10 ∝s t2 ≥ 10 ∝s

#### 2.Internal block states during the reset period.

#### • CLOCK GENERATOR

Reset is applied and the basic clock is stopped. (The oscillator on the OSC pin is stopped.)

#### • KEY SCAN, KEY BUFFER

Reset is applied, the circuit is set to the initial state, and at the same time the key scan operation is disabled.

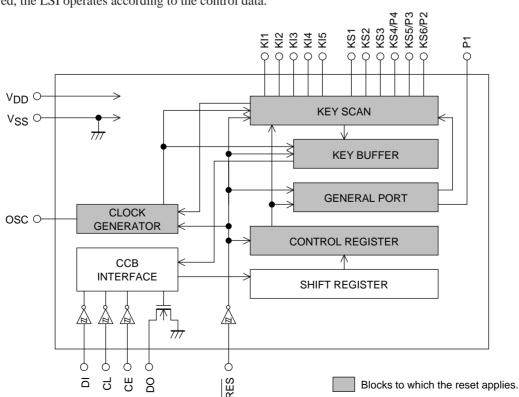
And all the key data is set to Low. Then, when the control data are transferred, the key scanning operation is enabled.

#### • GENERAL PORT

Reset is applied and the outputs of P1 to P4 are all set to the low level.

#### • CCB INTERFACE, SHIFT REGISTER, CONTROL REGISTER

When a reset is applied, The CONTROL REGISTER is forcibly initialized internally. Then, when control data are transferred, the LSI operates according to the control data.

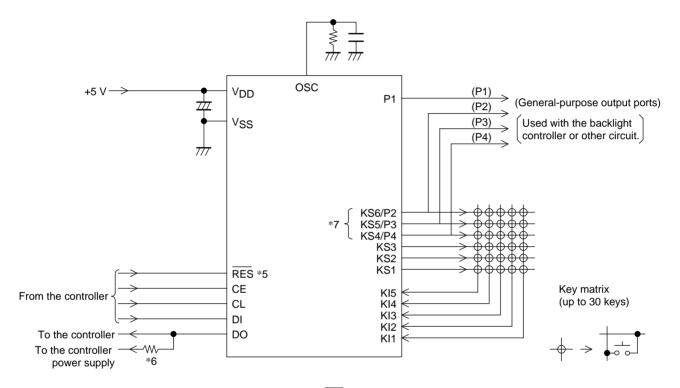


#### 3. Output pin states during a reset

| Output pins      | State during a reset |
|------------------|----------------------|
| KS1 to KS3       | L                    |
| KS4/P4 to KS6/P2 | L                    |
| P1               | L                    |
| DO               | H *4                 |

<sup>\*4.</sup> Since this output pin is an open-drain output, a pull-up resistor of between 1 and 10 kΩ is required. This pin remains high during the reset period even if a key data read operation is performed.

#### **Sample Application Circuit**



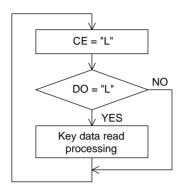
Note: \*5. When the power is first applied, it must be initialized by  $\overline{\text{RES}}$  = "L".

- \*6. The DO pin,being an open-drain output, requires a pull-up resistor. Select a resistance (between 1 and 10 kΩ) appropriate for the capacitance of the external wiring so that signal waveforms are not degraded.
- \*7. Each of The KS4/P4 to KS6/P2 pins must be set to either the key scan output port or the general-purpose output port.

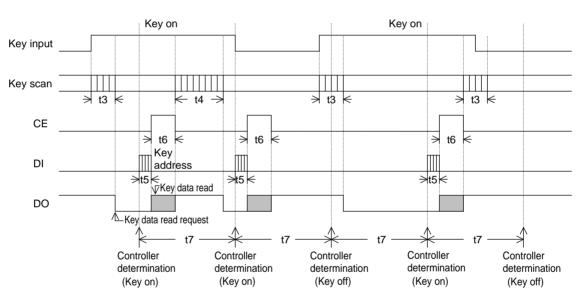
#### Notes on the controller key data read techniques

#### 1. Timer based key data acquisition

#### (1) Flowchart



#### (2) Timing chart



- t3: Key scan execution time when the key data agreed for two key scans (615T (s))
- t4: Key scan execution time when the key data did not agree for two key scans and the key scan was executed again. (1230T(s))
- t5: Key address (63H) transfer time
- t6: Key data read time

# $T = \frac{1}{\text{fosc}}$

#### (3) Explanation

In this technique, the controller uses a timer to determine key on/off states and read the key data. The controller must check the DO state when CE is low every t7 period without fail. If DO is low, the controller recognizes that a key has been pressed and executed the key data read operation.

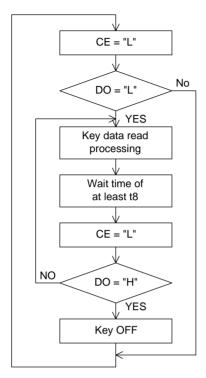
The period t7 in this technique must satisfy the following condition.

$$t7 > t4 + t5 + t6$$

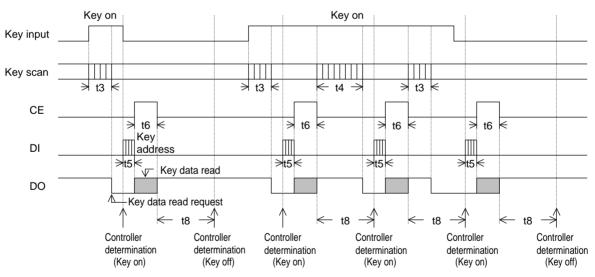
If a keydata read operation is executed when DO is high, the read key data (KD1 to KD30) will be invalid.

#### 2. Interrupt based key data acquisition

#### (1) Flowchart



#### (2) Timing chart



- t3: Key scan execution time when the key data agreed for two key scans (615T (s))
  t4: Key scan execution time when the key data did not agree for two key scans and the key scan was executed again. (1230T(s))
  t5: Key address (63H) transfer time
  t6: Key data read time

  T=

T= fosc

#### (3) Explanation

In this technique, the controller uses interrupts to determine key on/off states and read the key data. The controller must check the DO state when CE is low. If DO is low, the controller recognizes that a key has been pressed and executes the key data read operation. After that the next key on/off determination is performed after the time t8 has elapsed by checking the DO state when CE is low and reading the key data.

The period t8 in this technique must satisfy the following condition.

t8 > t4

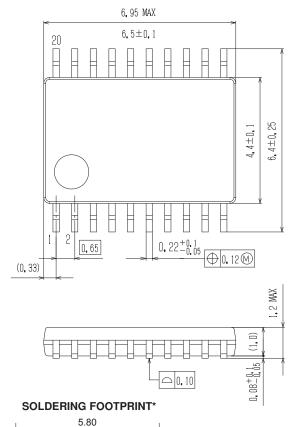
If a key data read operation is executed when DO is high, the read key data (KD1 to KD30) will be invalid.

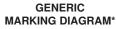
#### **PACKAGE DIMENSIONS**

unit: mm

#### TSSOP20 4.4x6.5 / TSSOP20 (225 mil)

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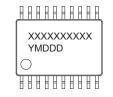




0 to 10°

 $0,5\pm 0$ 

 $0.15^{+0.1}_{-0.05}$ 



XXXXX = Specific Device Code Y = Year M = Month DDD = Additional Traceability Data

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTE: The measurements are not to guarantee but for reference only.

(Unit: mm)

0.32

\*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "•", may or may not be present.

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